

ECOFREC™ TF 37 – TF 37I



No-clean tacky & screen printable fluxes

FEATURES

ECOFREC™ TF37 & ECOFREC™ TF37I are tacky flux designed for **soldering and rework** of traditional components and SMDs.

Tacky fluxes **ECOFREC™ TF37 & ECOFREC™ TF37I** allow also metal-free soldering of SMDs on PCBs, the PCBs'solder pads being covered by about 100 microns of metal solid solder deposit (SSD technology such as SIPAD etc...). Designed for this technology, **ECOFREC™ TF37 & ECOFREC™ TF37I** exhibit good printing behaviour.

SPECIFICATIONS

	ECOFREC™ TF37	ECOFREC™ TF37I
Colour	amber	light yellow
Solubility	in water in alcohol	not soluble soluble
Classification according ANSI/J-STD-004	ROLO	ROLO
Halogen %	0	0
Density at 20°C	1	1
Viscosity at 20°C Pa.s <i>(Measured on BROOKFIELD RVT viscosimeter with Mobile F HELIPATH system, at 5 rpm)</i>	300 - 500	300 - 500

CHARACTERISTICS

Tacky fluxes **ECOFREC™ TF37 & ECOFREC™ TF37I** are high viscosity fluxes made of complex blending of resins, activators and solvents. After soldering, flux residues remaining on the PCB are non aggressive and not liable to corrosion. PCB cleaning is thus unnecessary.

ECOFREC™ TF37I has a stronger adhesive power than **ECOFREC™ TF37**.

PACKAGING

Plastic drum 100 g or 500 g

STORAGE & SHELF LIFE

Tacky fluxes **ECOFREC™ TF 37 & ECOFREC™ TF 37I** must be stored in a cool area (between 5° and 30°). Shelf life is about a year long.

PROCESS PARAMETERS

Tacky fluxes ECOFREC™ TF37 & ECOFREC™ TF37I can be applied by screen printing, using a stencil or a screen.

Deposits thickness is in the range of 100 microns.

The sticky properties of tacky fluxes ECOFREC™ TF37 & ECOFREC™ TF37I ensure that the components will be kept in position until the alloy is reflow using an IR or convection oven or vapour phase. After printing adhesive properties can be improved after 30-60 minutes storage or after heating at 50-60°C during few minutes.

A ready-to-use, prefluxed PCB can be stored several months, away from dust. In order to make storing easier, it is recommended that a non-stick paper be placed between these PCBs.

HSE

During soldering operations, evolving vapours should be collected by an efficient exhaust system.

No issues when used as recommended.

Although the conformity to ROHS 2011/65/EU applies to EQUIPMENT put on the market and not to a component in particular, we warranty that this product contains less than 0.1% of mercury, lead, chromium VI, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) and less than 0.01% for the cadmium, in accordance with the decision of The European Commission dated 18/08/2005, fixing the maximal concentration values.

This data is based on information that the manufacturer believe to be reliable and offered in good faith. In no event will INVENTEC be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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